

No clean leaded solder paste

SE/SS series



- Uses carefully classified solder powder with uniform particle size
- Superior workability, solderability and electrical reliability
- Applicable for super fine pitch SMT production

Product code definition

SE 48 - M956-2



Particle size definition

| Code | 48 | 58 |
|--------------------|---------|---------|
| Particle size (μm) | 20 - 45 | 20 - 38 |

Alloy code definition

| Code | Address term | Alloy composition (%) | Melting point (°C) |
|------|-----------------|-----------------------|--------------------|
| SE | Eutectic | Sn 37Pb | 183 |
| SS | 2.0% Ag content | Sn 36Pb 2.0Ag | 179-190 |

Characteristics of main products

- SE48-M956-2** Outstanding continual and intermittent printability even with fine pitch pattern (0.4mm pitch, 0.25mmφ) applications
- SE48-A230** Flux residue cleanable with Vigon A250 at 55 - 60°C. Stable printability with superior melting properties
- SS48-M955LV** Low voiding type. Reduces voiding regardless of component type, such as BGA and PwTr

Product performance

Performance of SE48-M956-2

| Printability | | Wettability | | Voiding property (PwTr) | |
|------------------------|-----------|-------------------|-------|-------------------------|-------------|
| QFP 0.2W-0.2G | CSP Φ0.25 | CSP Φ0.25 | R6330 | Conventional | SE48-M956-2 |
| | | | | | |
| Sharp print definition | | Excellent wetting | | | |

Product specifications

| Product name | SE48-M956-2 | SE48-A230 | SS48-M955LV |
|-----------------------|--|--------------------------------------|--|
| Alloy composition (%) | Sn 37Pb | Sn 37Pb | Sn 36Pb 2.0Ag |
| Melting point (°C) | 183 | 183 | 179-190 |
| Particle size (μm) | 20-45 | 20-45 | 20-45 |
| Viscosity (Pa.s) | 200 | 210 | 190 |
| Flux content (%) | 10.0 | 10.0 | 9.2 |
| Halide content (%) | 0.0 | 0.0 | 0.0 |
| Flux type | ROL0 | ROL1 | ROL0 |
| Optional powder size | 20-38μm (Product name: SE58-M956-2) | 20-38μm (Product name: SE58-A230) | 20-38μm (Product name: SS58-M955LV) |